

Trench gate field-stop IGBT, HB series 650 V, 20 A high speed

Datasheet - production data

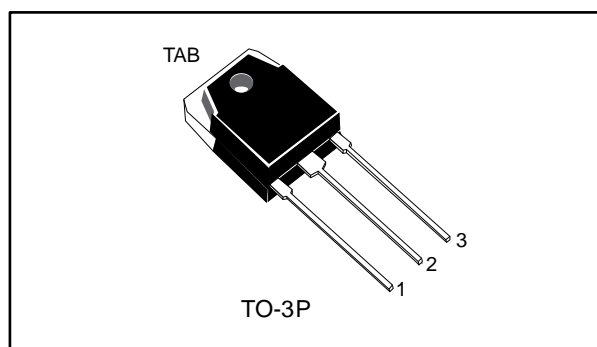
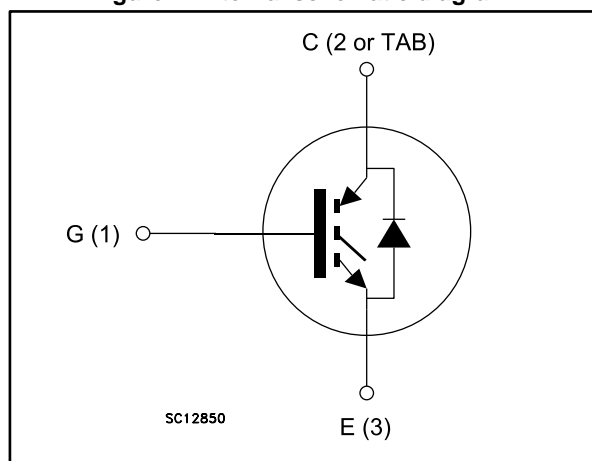


Figure 1: Internal schematic diagram



Features

- Maximum junction temperature: $T_J = 175\text{ }^\circ\text{C}$
- Minimized tail current
- $V_{CE(sat)} = 1.55\text{ V (typ.) @ } I_C = 20\text{ A}$
- Tight parameter distribution
- Co-packed diode for protection
- Safe paralleling
- Low thermal resistance

Applications

- Power factor corrector (PFC)

Description

This device is an IGBT developed using an advanced proprietary trench gate field-stop structure. The device is part of the new HB series of IGBTs, which represents an optimum compromise between conduction and switching loss to maximize the efficiency of any frequency converter. Furthermore, the slightly positive $V_{CE(sat)}$ temperature coefficient and very tight parameter distribution result in safer paralleling operation.

Table 1: Device summary

Order code	Marking	Package	Packing
STGWT20HP65FB	GWT20HP65FB	TO-3P	Tube

Contents

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1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CES}	Collector-emitter voltage ($V_{GE} = 0$ V)	650	V
I_C	Continuous collector current at $T_C = 25$ °C	40	A
	Continuous collector current at $T_C = 100$ °C	20	
$I_{CP}^{(1)}$	Pulsed collector current	80	A
V_{GE}	Gate-emitter voltage	± 20	V
I_F	Continuous forward current at $T_C = 25$ °C ⁽²⁾	5	A
	Continuous forward current at $T_C = 100$ °C	5	
$I_{FP}^{(3)}$	Pulsed forward current	10	A
P_{TOT}	Total dissipation at $T_C = 25$ °C	168	W
T_{STG}	Storage temperature range	-55 to 150	°C
T_J	Operating junction temperature range	-55 to 175	

Notes:

(1) Pulse width limited by maximum junction temperature

(2) Limited by wires

(3) Pulsed forward current

Table 3: Thermal data

Symbol	Parameter	Value	Unit
R_{thJC}	Thermal resistance junction-case IGBT	0.9	°C/W
R_{thJC}	Thermal resistance junction-case diode	5	
R_{thJA}	Thermal resistance junction-ambient	50	

2 Electrical characteristics

$T_J = 25\text{ °C}$ unless otherwise specified

Table 4: Static characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)CES}$	Collector-emitter breakdown voltage	$V_{GE} = 0\text{ V}$, $I_C = 2\text{ mA}$	650			V
$V_{CE(sat)}$	Collector-emitter saturation voltage	$V_{GE} = 15\text{ V}$, $I_C = 20\text{ A}$		1.55	2.0	V
		$V_{GE} = 15\text{ V}$, $I_C = 20\text{ A}$, $T_J = 125\text{ °C}$		1.65		
		$V_{GE} = 15\text{ V}$, $I_C = 20\text{ A}$, $T_J = 175\text{ °C}$		1.75		
V_F	Forward on-voltage	$I_F = 5\text{ A}$		2		V
		$I_F = 5\text{ A}$, $T_J = 125\text{ °C}$		1.85		
		$I_F = 5\text{ A}$, $T_J = 175\text{ °C}$		1.75		
$V_{GE(th)}$	Gate threshold voltage	$V_{CE} = V_{GE}$, $I_C = 1\text{ mA}$	5	6	7	V
I_{CES}	Collector cut-off current	$V_{GE} = 0\text{ V}$, $V_{CE} = 650\text{ V}$			25	μA
I_{GES}	Gate-emitter leakage current	$V_{CE} = 0\text{ V}$, $V_{GE} = \pm 20\text{ V}$			± 250	nA

Table 5: Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{ies}	Input capacitance	$V_{CE} = 25\text{ V}$, $f = 1\text{ MHz}$, $V_{GE} = 0\text{ V}$	-	2764	-	pF
C_{oes}	Output capacitance		-	80	-	
C_{res}	Reverse transfer capacitance		-	60	-	
Q_g	Total gate charge	$V_{CC} = 520\text{ V}$, $I_C = 20\text{ A}$, $V_{GE} = 15\text{ V}$ (see Figure 27: "Gate charge test circuit")	-	120	-	nC
Q_{ge}	Gate-emitter charge		-	20	-	
Q_{gc}	Gate-collector charge		-	50	-	

Table 6: IGBT switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(off)}$	Turn-off delay time	$V_{CE} = 400\text{ V}$, $I_C = 20\text{ A}$, $V_{GE} = 15\text{ V}$, $R_G = 10\ \Omega$ (see Figure 26: "Test circuit for inductive load switching")	-	139	-	ns
t_f	Current fall time		-	20	-	ns
$E_{off}^{(1)}$	Turn-off switching energy		-	170	-	μJ
$t_{d(off)}$	Turn-off-delay time	$V_{CE} = 400\text{ V}$, $I_C = 20\text{ A}$, $V_{GE} = 15\text{ V}$, $R_G = 10\ \Omega$, $T_J = 175\text{ °C}$ (see Figure 26: "Test circuit for inductive load switching")	-	147	-	ns
t_f	Current fall time		-	38	-	ns
$E_{off}^{(1)}$	Turn-off switching energy		-	353	-	μJ

Notes:

⁽¹⁾Including the tail of the collector current

Table 7: Diode switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
t_{rr}	Reverse recovery time	$I_F = 5\text{ A}$, $V_R = 400\text{ V}$, $V_{GE} = 15\text{ V}$, $di/dt = 1000\text{ A}/\mu\text{s}$ (see Figure 26: "Test circuit for inductive load switching")	-	140	-	ns
Q_{rr}	Reverse recovery charge		-	21	-	nC
I_{rrm}	Reverse recovery current		-	6.6	-	A
dl_{rr}/dt	Peak rate of fall of reverse recovery current during t_b		-	430	-	A/ μs
E_{rr}	Reverse recovery energy		-	1.6	-	μJ
t_{rr}	Reverse recovery time	$I_F = 5\text{ A}$, $V_R = 400\text{ V}$, $V_{GE} = 15\text{ V}$, $T_J = 175\text{ }^\circ\text{C}$, $di/dt = 1000\text{ A}/\mu\text{s}$ (see Figure 26: "Test circuit for inductive load switching")	-	200	-	ns
Q_{rr}	Reverse recovery charge		-	47.3	-	nC
I_{rrm}	Reverse recovery current		-	9.6	-	A
dl_{rr}/dt	Peak rate of fall of reverse recovery current during t_b		-	428	-	A/ μs
E_{rr}	Reverse recovery energy		-	3.2	-	μJ

2.1 Electrical characteristics (curves)

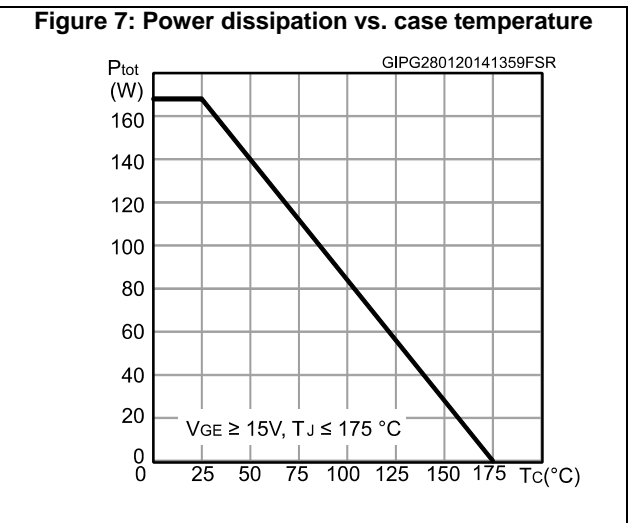
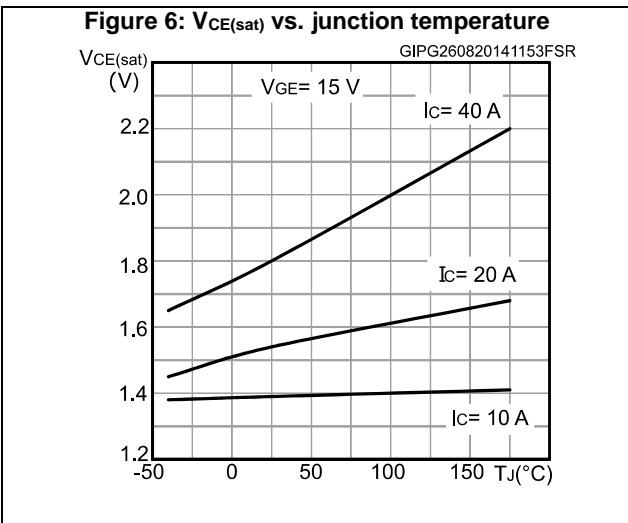
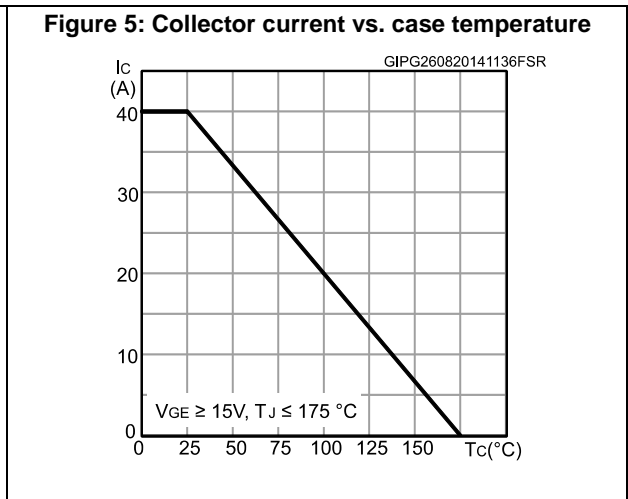
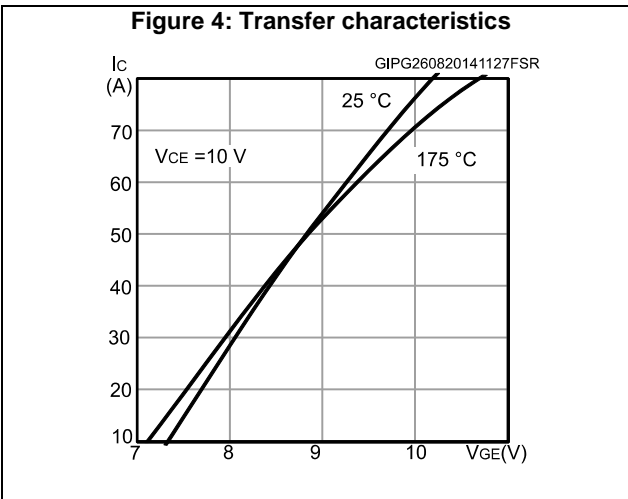
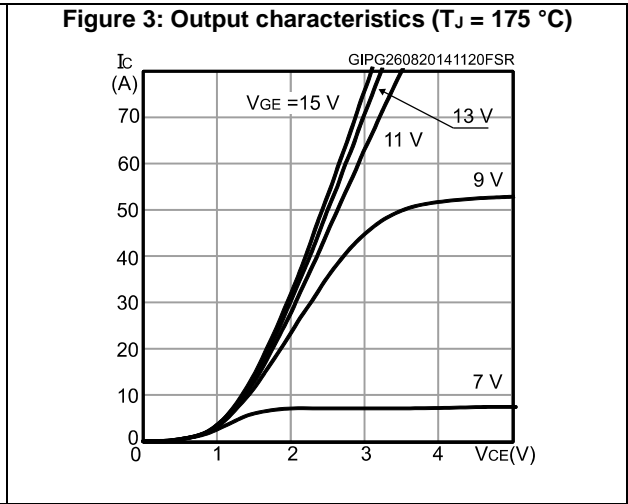
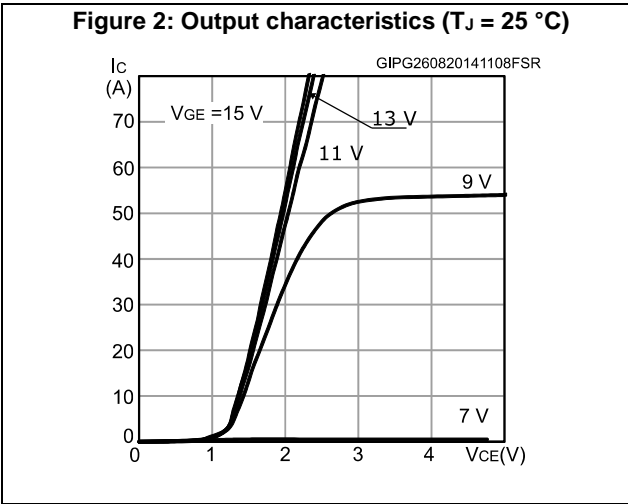


Figure 8: Forward bias safe operating area

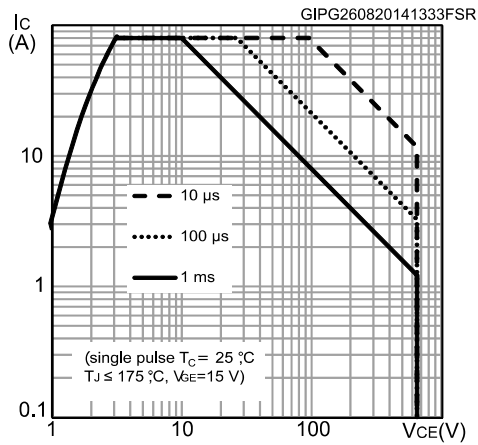


Figure 9: Collector current vs. switching frequency

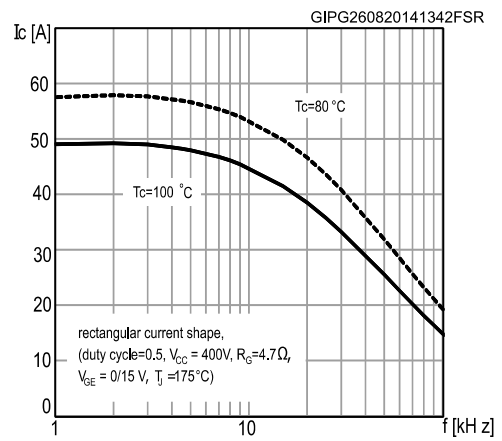


Figure 10: Normalized $V_{GE(th)}$ vs. junction temperature

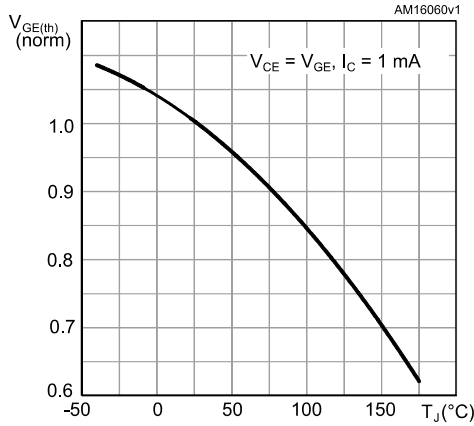


Figure 11: Normalized $V_{(BR)CES}$ vs. junction temperature

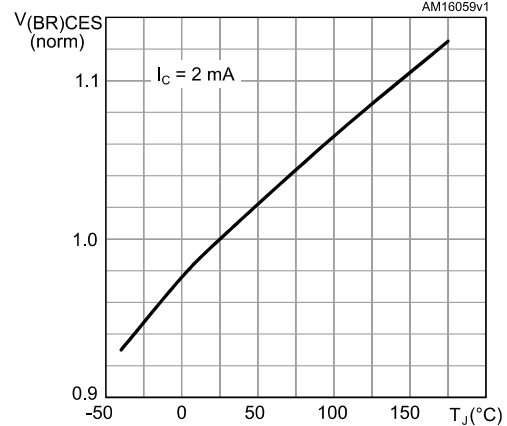


Figure 12: Switching energy vs. collector current

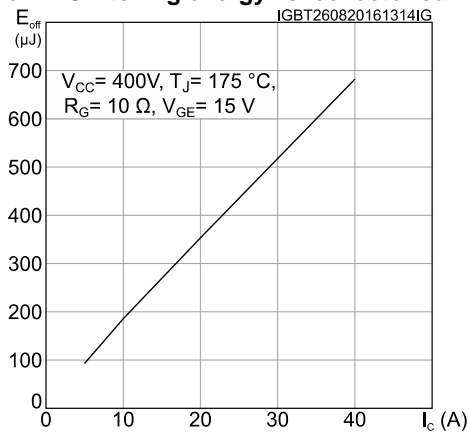


Figure 13: Switching energy vs. gate resistance

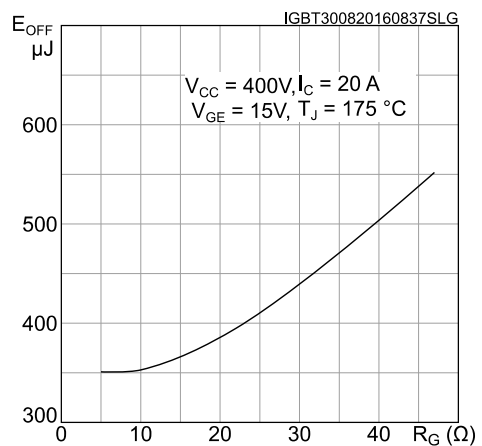


Figure 14: Switching energy vs. temperature

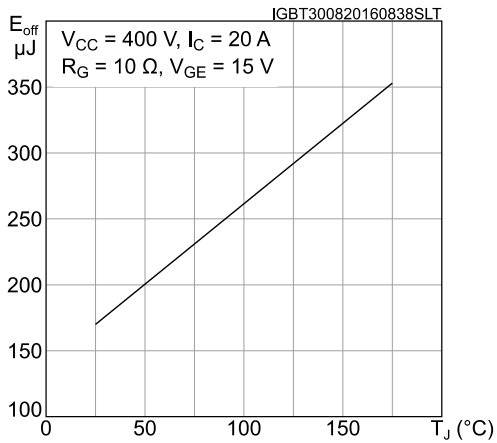


Figure 15: Switching energy vs. collector emitter voltage

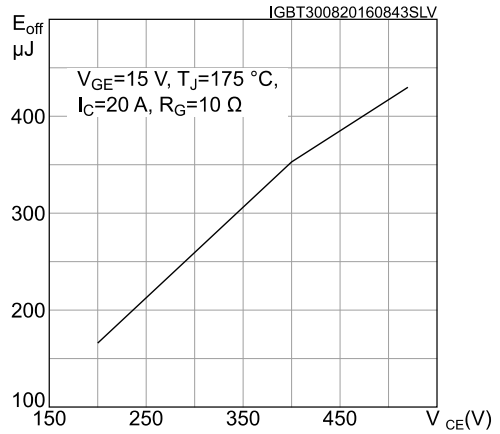


Figure 16: Switching times vs. collector current

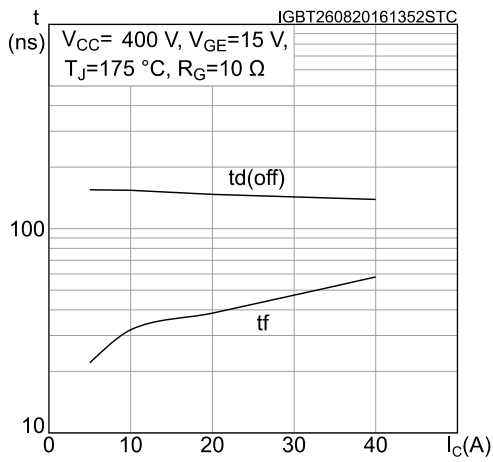


Figure 17: Switching time vs. gate resistance

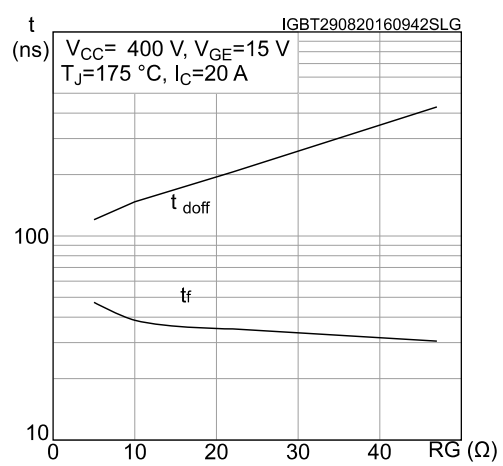


Figure 18: Capacitance variations

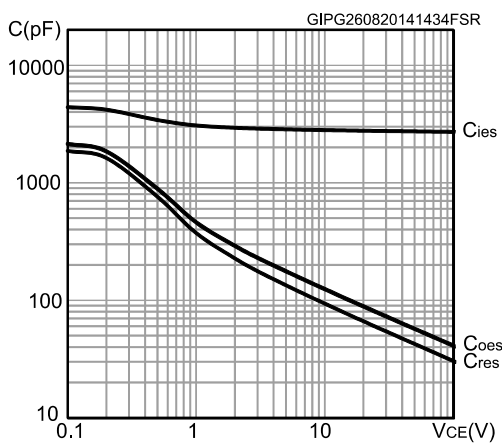
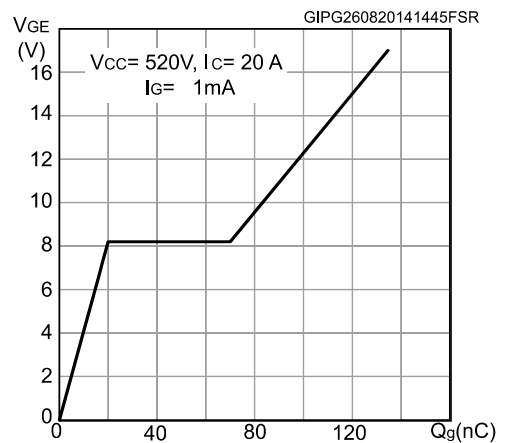
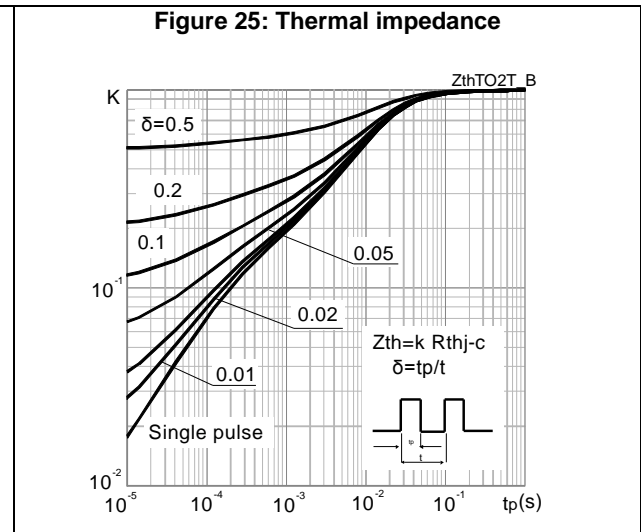
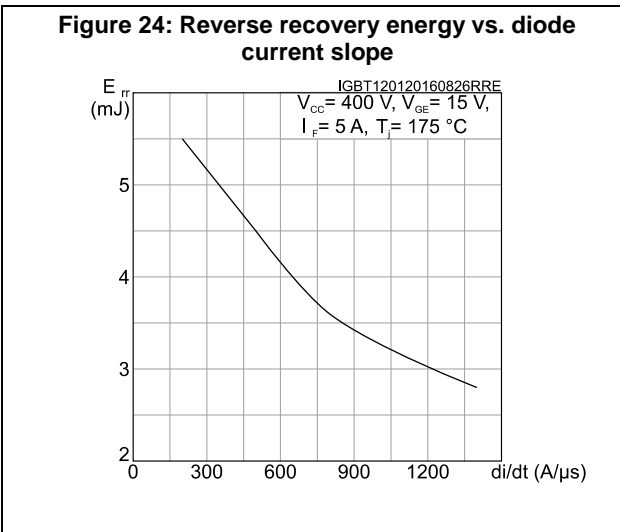
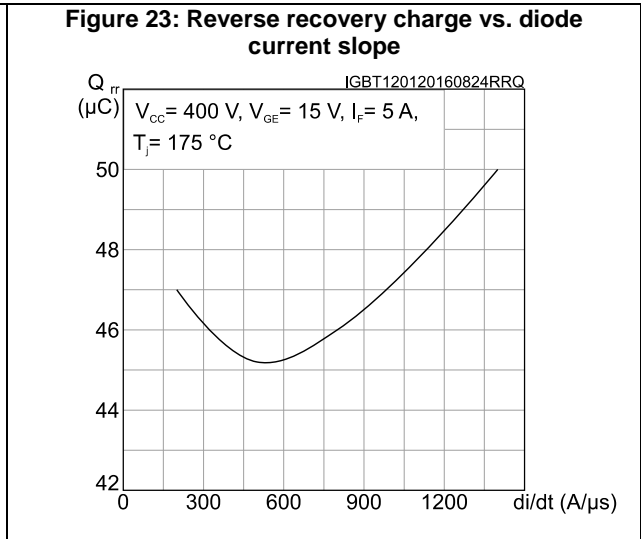
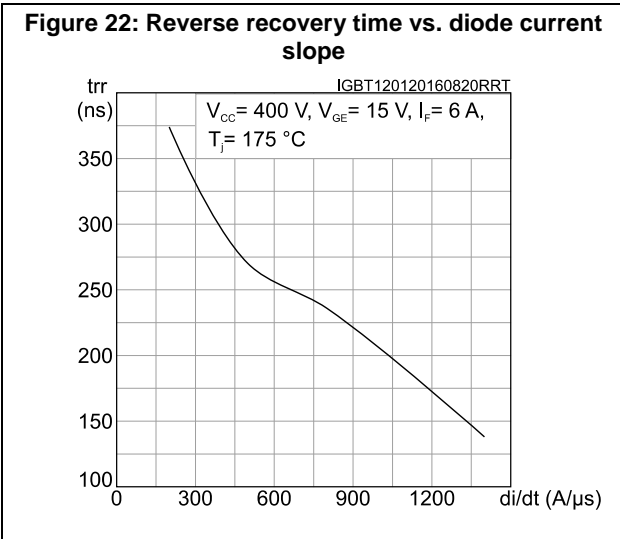
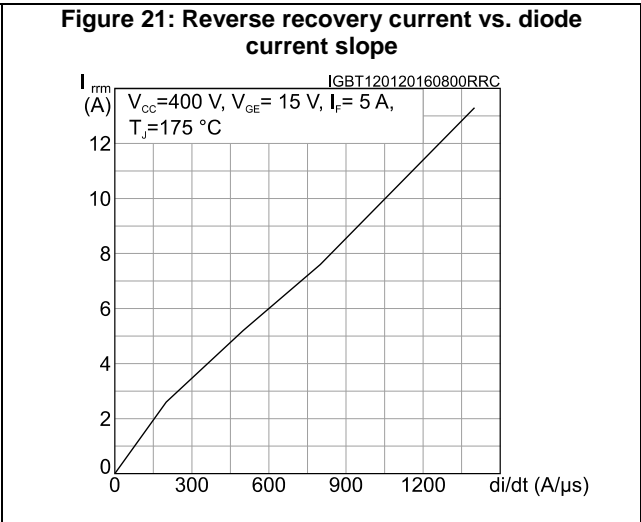
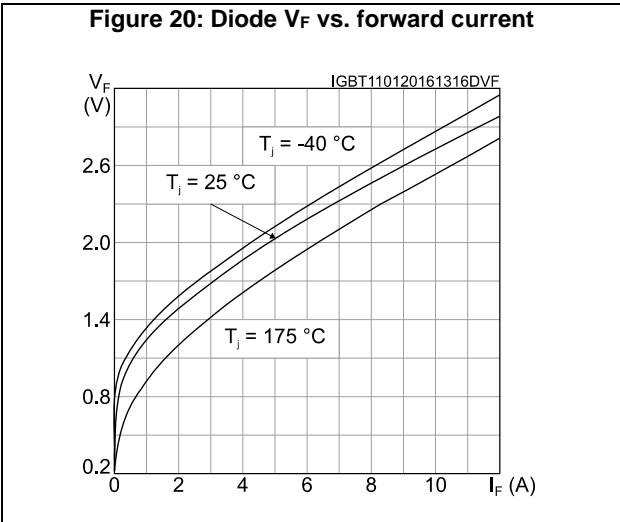


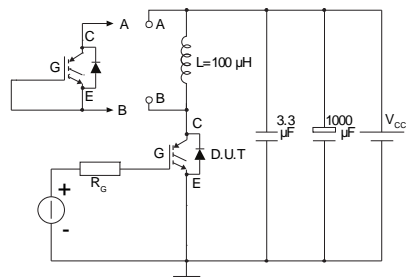
Figure 19: Gate charge vs. gate-emitter voltage





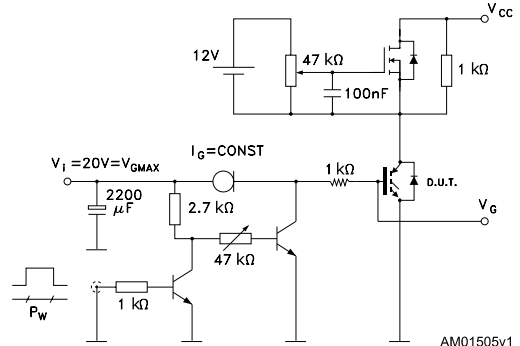
3 Test circuits

Figure 26: Test circuit for inductive load switching



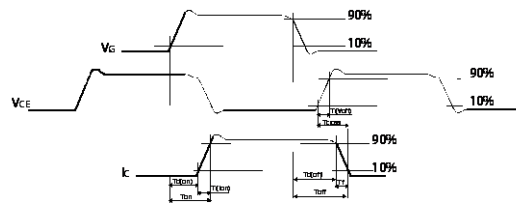
AM01504v1

Figure 27: Gate charge test circuit



AM01505v1

Figure 28: Switching waveform



AM01506v1

4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 TO-3P package information

Figure 29: TO-3P package outline

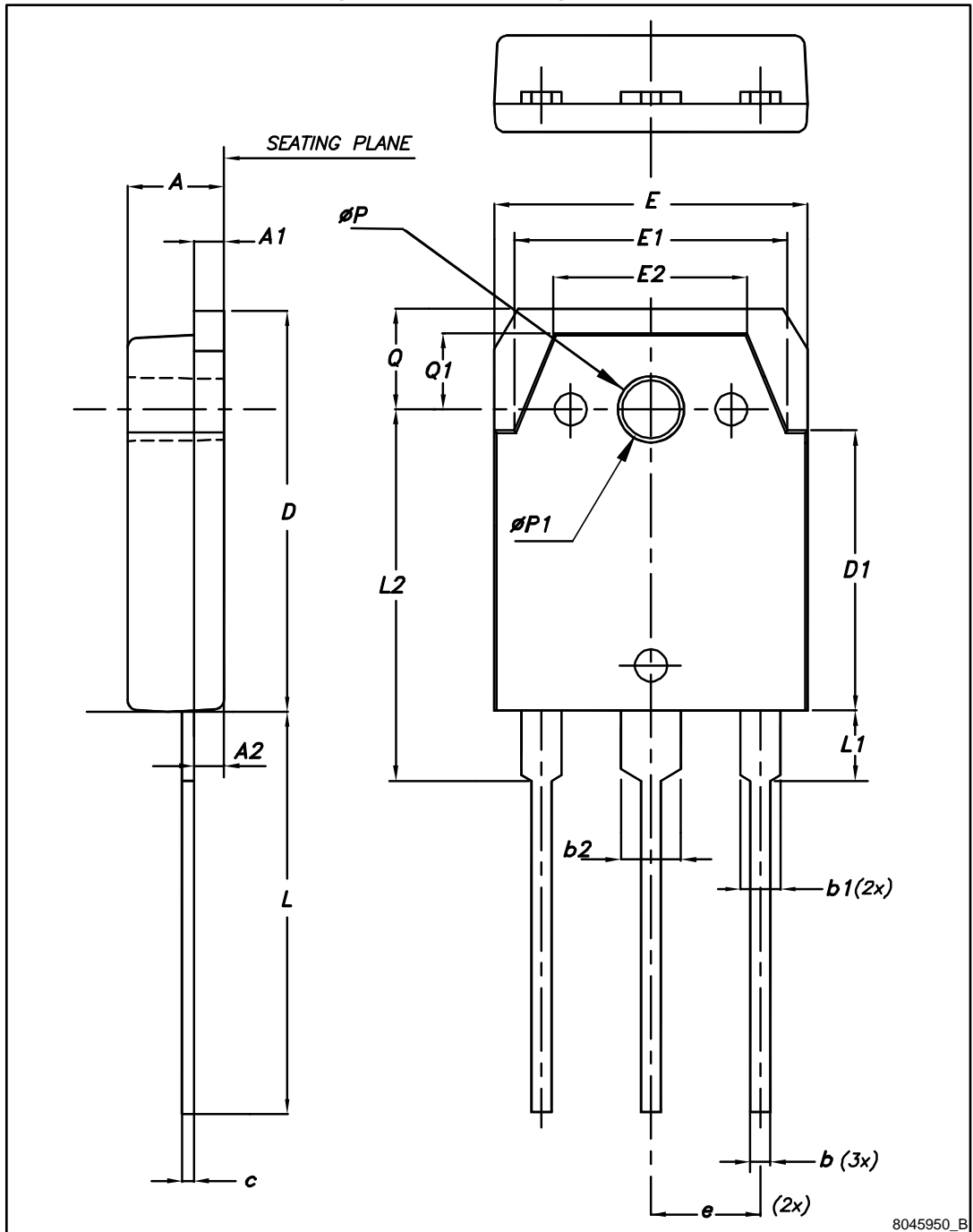


Table 8: TO-3P package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.60	4.80	5.00
A1	1.45	1.50	1.65
A2	1.20	1.40	1.60
b	0.80	1.00	1.20
b1	1.80	2.00	2.20
b2	2.80	3.00	3.20
c	0.55	0.60	0.75
D	19.70	19.90	20.10
D1	13.70	13.90	14.10
E	15.40	15.60	15.80
E1	13.40	13.60	13.80
E2	9.40	9.60	9.90
e	5.15	5.45	5.75
L	19.80	20.00	20.20
L1	3.30	3.50	3.70
L2	18.20	18.40	18.60
ØP	3.30	3.40	3.50
ØP1	3.10	3.20	3.30
Q	4.80	5.00	5.20
Q1	3.60	3.80	4

5 Revision history

Table 9: Document revision history

Date	Revision	Changes
31-Aug-2016	1	First release.
28-Sep-2016	2	Datasheet promoted from preliminary to production data.
13-Dec-2016	3	<p>Updated Figure 1: "Internal schematic diagram".</p> <p>Updated Table 4: "Static characteristics" and Table 7: "Diode switching characteristics (inductive load)".</p> <p>Added Figure 20: "Diode VF vs. forward current", Figure 21: "Reverse recovery current vs. diode current slope", Figure 22: "Reverse recovery time vs. diode current slope", Figure 23: "Reverse recovery charge vs. diode current slope" and Figure 24: "Reverse recovery energy vs. diode current slope".</p> <p>Updated Figure 2: "Output characteristics (T_J = 25 °C)", Figure 12: "Switching energy vs. collector current" and Figure 17: "Switching time vs. gate resistance".</p> <p>Minor text changes</p>

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